| "Contained In" % Total mg/part mg/part ppm 263.40 (mg) Total Mold Compound % ot Total Weight 74.03 Basic Substance 60676-86-0 Mold Compound 65.346 232.502 653,463 Silica Fused 60676-86-0 88.27 Silica Fused Trade Secret Mold Compound 4.619 16.436 46,195 Epoxy Resin Trade Secret 624 Phenol Resin Trade Secret Mold Compound 3.842 13.670 38,422 Phenol Resin Trade Secret 6.24 Carbon Black 1333-86-4 Mold Compound 0.222 0.790 2,221 Carbon Black 1333-864 0.00 Copper 7440-50-8 Lead Frame 21.324 75.872 213,245 Total 00.00 | Semiconductor Device Type: CGA 80 LQFP 10x10x1.4mm Matte Tin | | | | Termination Base Alloy: Copper Alloy (Cu) | | | Package Homogeneous Materials | | | | |
|--|--|--|---|--|--|---|--------|--|---|--|------------|---|
| User Cub Addition Verifyit Implant Open Control of the control | | | | | | | 000.40 | () T =4=1 | Mold Common d | N/ at Tatal Mainta | 74.00 | |
| $ \frac{1}{1000} \frac{1}{100$ | Basic Substance | CAS Number | Sub-Component | Weight | mg/part | ppm | 263.40 | (mg) I otal | Mold Compound | % of Total Weight | 74.03 | |
| Plenck Ream Trade Secure Mod Compound 3.242 3.870 3.84.22 Composition Composi | Silica Fused | 60676-86-0 | Mold Compound | 65.346 | 232.502 | 653,463 | | Silica Fused | 60676-86-0 | 88.27 | | |
| Carbon Black 1333 88-4 Mode Compound 0.222 0.780 2.231 (mail 1333 86-4) 0.33 Copper 7446 0-06 Lasel Frame 0.133 76.6 2.231 (mail 133 86-4) 0.33 Mission 7446 0-05 Lasel Frame 0.136 1.081 (mail 133 86-4) 0.301 Magnetian 7446 0-13 Lasel Frame 0.102 2.038 724 (mail 133 86-4) 0.301 Magnetian 7446 0-24 Dia Atach 0.401 2.436 1.088 < | Epoxy Resin | Trade Secret | | | | | | Epoxy Resin | Trade Secret | | | |
| Copper 7440-00-0 Lead Frame 0.21.324 75.872 213.24 <t< td=""><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td><td></td></t<> | | | | | | | | | | | | |
| Noise 744022-0 Lead Frame 0.569 2023 5.677 78.6 (mg) Total Lead Frame 5.97 744024-0 6.10 744024-0 6.10 744024-0 6.10 744024-0 6.10 744024-0 6.10 744024-0 6.10 744024-0 6.10 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 744024-0 | | | | | | | | Carbon Black | 1333-86-4 | | Į | |
| Silver 7440:224 Lead Frame 0.374 1.330 3.777 7440:213 Lead Frame 0.111 0.358 1.080 7440:214 1.000 7440:213 1.000 | | | | | | | | | | | | |
| | Nickel | 7440-02-0 | Lead Frame | 0.569 | 2.023 | 5,687 | 79.66 | (mg) Total | Lead Frame | % of Total Weight | 22.39 | |
| Magnetium 7480/95/4 Liad Frame 0.022 0.080 224 Shiver (AQ) 7440/25/4 De Attach 0.034 1.740 3.44 1.740 3.44 1.740 3.44 1.740 3.44 1.740 3.44 1.740 3.44 1.740 3.44 1.740 3.44 1.740 3.44 1.740 3.44 1.740 3.44 1.740 3.44 1.740 3.74 1.740 3.74 1.740 3.74 1.740 3.74 1.740 1.740 3.74 1.740 3.74 1.740 3.74 1.740 3.74 1.740 3.74 1.740 1.740 3.74 1.740 1.740 3.74 1.740 7.440 2.44 3.78 1.750 1.750 1.750 1.740 3.74 1.760 3.78 1.750 1.750 1.750 1.760 3.78 1.750 1.760 7.440 2.44 3.40 7.440 2.44 3.40 7.440 2.44 3.40 7.440 2.44 | Silver | 7440-22-4 | Lead Frame | 0.374 | 1.330 | 3,737 | | Copper | 7440-50-8 | 95.24 | | |
| Siltor (A) 7440-22-4 De Attach 0.339 1.240 3.486 Acrystate Resin Trade Secret Die Attach 0.038 0.134 378 Epoxy Resin Trade Secret Die Attach 0.032 0.032 231 Trade Secret 0.000 Silcon 7440-21-3 Chip (Die) 1.860 231 Trade Secret 0.000 0.001 0.032 1.03 Trade Secret 0.000 0.0 | Silicon | | Lead Frame | | | | | Nickel | 7440-02-0 | 2.54 | | |
| Acytal Rein Trade Scoret Die Attach 0.038 0.134 378 Magnesum 7439-84-3 0.103 Epoor Resin 9003-36-5 Die Attach 0.023 0.082 231 (mg) Total Die Attach % of Total Weight 0.42 Silicon 7440-22-4 Chyper 7440-22-4 Chyper 7440-22-4 83.00 Acytaie Resin 1.09 (mg) Total Die Attach % of Total Weight 0.42 Paladium 7440-22-4 Chyper 7440-22-4 0.02 0.78 0.00 778 0.00 778 0.00 778 0.00 778 0.00 778 0.00 778 0.00 778 0.00 778 0.00 778 0.00 778 0.00 778 0.00 0. | Magnesium | | Lead Frame | 0.022 | | 224 | | Silver | 7440-22-4 | | | |
| Encody Real Trade Sacret Die Attach 0.033 0.032 231 Trade Trade< | Silver (Ag) | | | | | | | Silicon | | | | |
| Epopy Resin 9003 36-5 Die Attach 0.011 0.037 105 1.40 (mg) Tesit Die Attach % of Tesit Weight 0.42 Copper 7440 25-8 Wire Bond 0.245 0.872 2.450 Arytan Rean Table Screet 8.00 Paliadum 7440 25-8 Wire Bond 0.0245 0.872 2.450 Arytan Rean Table Screet 8.00 Tim 7440 25-8 Wire Bond 0.000 35.80 1.000,000 Arytan Rean Table Screet 8.00 Emiconductor device and its homogenous materials comply with EU Directives: 2002/SEC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March and 2002/863/2562 (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March and 2002/863/256) Fotal Total 100.00 ancid substance is absent of the data of this design controls, supplier declarations, and /or analytical test data. Import of the data of this design controls, supplier declarations, and /or analytical test data. Total 0.89 (mg) Total Wire Bond % of Total Weight 0.25 ancid substance is absent wrifted wire in orchiple reason to believe that the unavoidable impurity concentris on the bast of Mirocchip Technology | Acrylate Resin | Trade Secret | Die Attach | 0.038 | 0.134 | 378 | | Magnesium | 7439-95-4 | 0.10 | | |
| Silion744021-3Chy (b)1.8006.61818.000Silicon744022488.00Copper744025-8Wire Bond0.2540.8722.4500.01850Tin744021-7Wire Bond0.0050.73610.00035.58010.000Epoxy ResinTrade Secret5.50Total Secret5.00Total SecretTotal Secret <td colsp<="" td=""><td>Epoxy Resin</td><td>Trade Secret</td><td>Die Attach</td><td>0.023</td><td>0.082</td><td>231</td><td></td><td></td><td>Total</td><td>100.00</td><td></td></td> | <td>Epoxy Resin</td> <td>Trade Secret</td> <td>Die Attach</td> <td>0.023</td> <td>0.082</td> <td>231</td> <td></td> <td></td> <td>Total</td> <td>100.00</td> <td></td> | Epoxy Resin | Trade Secret | Die Attach | 0.023 | 0.082 | 231 | | | Total | 100.00 | |
| Copper 7440-50-8 Wire Bond 0.343 0.872 2.490 Tin 7440-50-3 Wire Bond 0.000 0.116 50 Tin 7440-31-5 Palladum 7440-31-5 Palladum 7440-31-5 9.00 0.3558 01 7440-31-5 Palladum 7440-31-5 Palladum 7440-31-5 9.00 0.3558 01 Outper 7440-31-5 Palladum 7440-31-5 Palladum 7440-31-5 9.00 0.3558 01 Outper 7440-31-5 Palladum 7440-31-5 9.00 <td< td=""><td>Epoxy Resin</td><td>9003-36-5</td><td>Die Attach</td><td>0.011</td><td>0.037</td><td>105</td><td>1.49</td><td>(mg) Total</td><td>Die Attach</td><td>% of Total Weight</td><td>0.42</td></td<> | Epoxy Resin | 9003-36-5 | Die Attach | 0.011 | 0.037 | 105 | 1.49 | (mg) Total | Die Attach | % of Total Weight | 0.42 | |
| Pailadium 7440:05:3 Wrie Bond 0.005 0.018 50 Tin 7440:31:5 Plaing on external lasting (pm) Total 100:00 355.800 1,000.00 Total 100:000 O .3558 g. Total Mass Colspan="2">Colspan="2" Colspan="2">Colspan="2" Colspan="2" | Silicon | 7440-21-3 | Chip (Die) | 1.860 | 6.618 | 18.600 | | Silver (Ag) | 7440-22-4 | 83.00 | ľ | |
| Tin Tell | Copper | 7440-50-8 | Wire Bond | 0.245 | 0.872 | 2,450 | | Acrylate Resin | Trade Secret | 9.00 | | |
| TOTALS: 100.000 335.800 1,000,000 Total Total 1000,000 0.3558 g Total Mass 0.3558 g Total Mass Total (mg) Chip (Die) % of Total Weight 1.86 semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27) anuary 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March and 2002/93/EC (End-d-Life Vehicles (EU) without exemption (zero) Deped Silicon 7440-21-3 100.00 incress with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. Total Deped Silicon 7440-21-3 100.00 ing compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at //Locom/global/engages/offerings/industries/chemicals/plastics/ 0.89 (mg) Total Wire Bond % of Total Weight 0.25 ing compounds used by Microchip meet the base off from PVC plastic. Winden ablef as of the date fisted in his form. Nicrochip Technology incorporated believes the information in this form concerning substance restricted by ROHS in Microchip Technology incorporated meet has been completed hader of the stoge off the date issed in this form. Nicrochip Technology incorporated cannot guarantee the planeting and the renses and accuracy of data in this form mecane weight of the stop stop and belows the information may not have been provided by subcontract asembers and remeratel sup | Palladium | 7440-05-3 | Wire Bond | 0.005 | 0.018 | 50 | | Epoxy Resin | Trade Secret | 5.50 | 1 | |
| TOTALS: 100.00 355.800 100.000 OTALS: 100.000 355.800 100.000 Semiconductor devices and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March and 2002/87/EC (4not-Life Vehicles (ELV) without exemption (zero) Colspan="2">Colspan="2">Colspan="2">Colspan="2">Colspan="2">Colspan="2">Colspan="2">Colspan="2">Colspan="2">Colspan="2">Colspan="2">Colspan="2">Colspan="2">Colspan="2">Colspan="2">Colspan="2" Total Sister Colspan="2" Total Mass Total Mass Colspan="2" Colspan="2" Colspan="2" Colspan="2" Total Mass Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" Colspan="2" <th co<="" td=""><td>Tin</td><td>7440-31-5</td><td>Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour</td><td>1.050</td><td>3.736</td><td>10,500</td><td></td><td>Epoxy Resin</td><td>9003-36-5</td><td>2.50</td><td>1</td></th> | <td>Tin</td> <td>7440-31-5</td> <td>Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour</td> <td>1.050</td> <td>3.736</td> <td>10,500</td> <td></td> <td>Epoxy Resin</td> <td>9003-36-5</td> <td>2.50</td> <td>1</td> | Tin | 7440-31-5 | Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour | 1.050 | 3.736 | 10,500 | | Epoxy Resin | 9003-36-5 | 2.50 | 1 |
| semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) plance with the above EU Directives has been verified via internal design controls, supplier declarations, and <i>i</i> or analytical test data. namical substance is absent from the list above, the chemical substance is NOT an intennional ingredient in the semiconductor device and, to the best of Microchip Technology porated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if no toblow the threshold of regulatory concern for any regulatory scheme world-wide. Ing compounds used by Microchip meet the UL44 V0 fimmability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at (ulcom/globale/ng/ages/offerings/industries/chemicals/plastics/ rotective "tubes" in which the specific product is shipped are made from polyinyl choride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and n' retesi" may be made from PVC plastic. Winde correct to the best of its knowledge and belief, as of the date listed in this form. Correchip Technology Incorporated from disclosures as trade secrets and some information may not have been provided in Material Starty Data Shead sprovided by material suppliers. Information is often protected from disclosures as trade secrets and some information may not have been provided in this form schemates of the average weight of anticipated significant tokic metals components. These estimates do not include trace levels anti, metals, and non-metal materials contained within silic on devices (silicon IC) in the finished parts. chip Technology Incorporated does not provide any warranty, scress or implied, with respect to the hieles to the information or sola. Total "Microchip's | | | | 100.000 | 355.800 | 1.000.000 | I | | Total | 100.00 | | |
| emiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) liance with the above EU Directives has been verified via internal design controls, supplier declarations, and <i>for</i> analytical test data. temical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology portacte ⁵ knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if no to below the threshold of regulatory concern for any regulatory scheme world-wide. In g compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at ULConfigibial/Biologi/Spage/Sofferings/industries/chemicals/plastics/ rotective "tubes" in which the specific product is shipped are made from polyinyl choride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and rivels' may be made from PVC plastic. chip Technology Incorporated believes the information in this form concerning substances restricted by RNS in Microchip Technology Incorporated cannot guarantee the leteness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Subeliers are trade sortate and within silicon devices (silicon IC) in the finished parts. chip Technology Incorporated does not provide and with subsidiaries are contained in Microchip's tandard terms and conditions of sale. These are provided in Microchip's tions, sales order achonoled provides and warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited portices as a result of the users' reliance on the information may not | | 0 2559 | a Totol Mass | | | ,, | 6.62 | Total (mg) | Chin (Dio) | 0/ of Total Mainh | 4.96 | |
| crated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if 0.89 (mg) Total Wire Bond % of Total Weight 0.25 not below the threshold of regulatory concern for any regulatory scheme world-wide. 0.89 (mg) Total Wire Bond % of Total Weight 0.25 g compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at Copper 7440-50-8 98.00 Icom/global/eng/pages/offerings/industries/chemical/plastics/ reals' may be made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and Palladum 7440-50-8 98.00 Ip Total View Total View Total View Total 100.00 Not below the threshold of regulatory concern for any regulatory scheme world-wide. 98.00 Palladum 7440-50-8 98.00 2.00 Ip Total Total 100.00 View Total 100.00 | | | : 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 | June 2011) a | nd 2015/863/EU | U (31 March | | | 7440-21-3 | 100 | | |
| //ui.com/global/eng/pages/offerings/industries/chemicals/plastics/ |) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption | (zero) | | June 2011) a | nd 2015/863/El | U (31 March | | | 7440-21-3 | 100 | | |
| 1 "reels" may be made from PVC plastic. Palladium 7440-05-3 2.00 hip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated cannot guarantee the eteness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Suppliers information is ed only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels ants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts. Palladium 7440-05-3 2.00 hip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in Microchip's standard terms and conditions of sale. These are provided in Microchip's is standard terms and conditions of sale. These are provided in Microchip's is standard terms and shall not be liable for any damages, direct or indirect, consequential or rise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or bied package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at Total 100.00 | and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption iance with the above EU Directives has been verified via interr emical substance is absent from the list above, the chemical s orated's knowledge and belief as of the date of this document not below the threshold of regulatory concern for any regulat | (zero) nal design contro ubstance is NOT , there is no cred ory scheme worl | Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ible reason to believe that the unavoidable impurity concent d-wide. | to the best of tration of the | Microchip Teo chemical subs | chnology | 0.89 | Doped Silicon | 7440-21-3 Total | 100 100.00 | | |
| chip Technology incorporated believes the information in this form concerning substances restricted by Korks in Microchip Technology incorporated is semiconductor devices in original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology incorporated cannot guarantee the leteness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier nation is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is ded only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels ants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts. chip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited product trites provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's trins, sales order acknowledgement, and invoices. chip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or wise, suffered by users or third parties as a result of the users' reliance on the information low Microchip Candidate list of ECHA which can be found at Total 100.00 | and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption liance with the above EU Directives has been verified via interr semical substance is absent from the list above, the chemical s borated's knowledge and belief as of the date of this document s not below the threshold of regulatory concern for any regulat ng compounds used by Microchip meet the UL94 V0 flammabil ul.com/global/eng/pages/offerings/industries/chemicals/plastic | (zero) nal design contro ubstance is NOT , there is no cred ory scheme worl ity standard for p .s/ | Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ible reason to believe that the unavoidable impurity concent d-wide. plastics. You can access the UL iQTM family of databases to | to the best of tration of the o obtain a test | Microchip Tec chemical subs report at | chnology stance, if | 0.89 | Doped Silicon (mg) Total | 7440-21-3 Total Wire Bond | 100 100.00 % of Total Weight | | |
| The performance provide any warrancy, express or implied, with respect to the information provided in this declaration. The exclusive, initiate product any warrancy, express or implied, with respect to the information provided in this declaration. The exclusive, initiate product any warrancy, express or implied, with respect to the information provided in this declaration. The exclusive, initiate product any warrancy, express or implied, with respect to the information provided in this declaration. The exclusive, initiate product any warrancy, express or implied, with respect to the information provided in this declaration. The exclusive, initiate product any warrancy, express or implied, with respect to the information provided in this declaration. The exclusive, initiate product any warrancy, express or implied, with respect to the information provided in this declaration. The exclusive, initiate product any declaration interview of the exclusive, initiate product any declaration into the exclusive, initiate product any declaration interview of the exclusive, initiate product any declaration interview of the exclusive, initiate product and interview of the exclusive of the exclusive, initiate | and 2002/53/EC (End-of-Life Vehicle's (ELV) without exemption pliance with the above EU Directives has been verified via interr hemical substance is absent from the list above, the chemical s porated's knowledge and belief as of the date of this document is not below the threshold of regulatory concern for any regulat ing compounds used by Microchip meet the UL94 V0 flammabil (ul.com/global/eng/pages/offerings/industries/chemicals/plastic protective "tubes" in which the specific product is shipped are n | (zero) nal design contro ubstance is NOT , there is no cred ory scheme worl ity standard for p .s/ | Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ible reason to believe that the unavoidable impurity concent d-wide. plastics. You can access the UL iQTM family of databases to | to the best of tration of the o obtain a test | Microchip Tec chemical subs report at | chnology stance, if | 0.89 | Doped Silicon (mg) Total Copper | Vire Bond 7440-50-8 7440-05-3 | 100 100.00 % of Total Weight 98.00 2.00 | 0.25 | |
| rwise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or models are sufficient to the users' reliance on the latest SVHC candidate list of ECHA which can be found at the found at the user's reports (SGS) or the user's reliance on the latest SVHC candidate list of ECHA which can be found at the user's reports (SGS) or the |) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified via interr hemical substance is absent from the list above, the chemical s prorated's knowledge and belief as of the date of this document is not below the threshold of regulatory concern for any regulat ling compounds used by Microchip meet the UL94 V0 flammabil //ul.com/global/eng/pages/offerings/industries/chemicals/plastic protective "tubes" in which the specific product is shipped are r in "reels" may be made from PVC plastic. ochip Technology Incorporated believes the information in this I original packing materials is true and correct to the best of its k pleteness and accuracy of data in this form because it has been mation is often protected from disclosure as trade secrets and a ided only as estimates of the average weight of these parts and | (zero) hal design contro ubstance is NOT there is no cred ory scheme worl ity standard for p s/ nade from polyvi form concerning nowledge and b compiled based some information | Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ible reason to believe that the unavoidable impurity concent d-wide. alastics. You can access the UL iQTM family of databases to nyl chloride (PVC) plastic. "Window envelopes" used to hol substances restricted by RoHS in Microchip Technology Im elief, as of the date listed in this form. Microchip Technology on the ranges provided in Material Safety Data Sheets provi n may not have been provided by subcontract assemblers an ht of anticipated significant toxic metals components. These | to the best of tration of the o obtain a test Id the packing corporated's y Incorporate ided by raw m | Microchip Ter chemical sub: report at g slip on the or semiconducto d cannot guara naterial suppliers. In | chnology stance, if uter box and or devices in antee the ers. Supplier nformation is | 0.89 | Doped Silicon (mg) Total Copper | Vire Bond 7440-50-8 7440-05-3 | 100 100.00 % of Total Weight 98.00 2.00 | 0.25 | |
| ://echa.europa.eu/web/guest/candidate-list-table | 5) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption apliance with the above EU Directives has been verified via interr chemical substance is absent from the list above, the chemical s prorated's knowledge and belief as of the date of this document is not below the threshold of regulatory concern for any regulat ding compounds used by Microchip meet the UL94 V0 flammabil ://ul.com/global/eng/pages/offerings/industries/chemicals/plastic protective "tubes" in which the specific product is shipped are r ain "reels" may be made from PVC plastic. rochip Technology Incorporated believes the information in this is roriginal packing materials is true and correct to the best of its k upleteness and accuracy of data in this form because it has been riation is often protected from disclosure as trade secrets and pided only as estimates of the average weight of these parts and opants, metals, and non-metal materials contained within silicon rochip Technology Incorporated does not provide any warranty, r ranties provided by Microchip Technology Incorporated and its s tations, sales order acknowledgement, and invoices. | (zero) hal design contro ubstance is NOT there is no cred ory scheme worl ity standard for p s/ nade from polyvi form concerning nowledge and b compiled based some informatior the average weig devices (silicon express or implie ubsidiaries are c | Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ible reason to believe that the unavoidable impurity concent d-wide. plastics. You can access the UL iQTM family of databases to nyl chloride (PVC) plastic. "Window envelopes" used to hol substances restricted by RoHS in Microchip Technology In- glief, as of the date listed in this form. Microchip Technology on the ranges provided in Material Safety Data Sheets provi may not have been provided by subcontract assemblers at ht of anticipated significant toxic metals components. Thes IC) in the finished parts. d, with respect to the information provided in this declarati- ontained in Microchip's standard terms and conditions of standard | to the best of tration of the o obtain a test Id the packing corporated's y Incorporate ided by raw m nd raw mater se estimates o on. The exclu ale. These are | Microchip Ter chemical sub: report at g slip on the or semiconducto d cannot guar- naterial suppliers. I do not include sive, limited p e provided in M | chnology stance, if uter box and or devices in antee the ers. Supplier information is trace levels product dicrochip's | | Doped Silicon (mg) Total Copper Palladium (mg) Total | 7440-21-3 Total Wire Bond 7440-50-8 7440-05-3 Total Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour | 100 100.00 % of Total Weight 98.00 2.00 100.00 % of Total Weight | 0.25 | |
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